L Number	Hits	Search Text	DB	Time stamp
1	5	(trench with (etch etching) and ((oxide dioxide) and nitride) with mask and removing with mask) and ((438/222,226,357,360,363,429,442,for.167,for.221).CCLS.) and @pd>=20040108	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/28 10:29
2	0	(amorphizing amorphization amorphized amorphous) with (ion implant implantation implanting implanted) same (trench groove recess recessed grooved) and ((438/222,226,357,360,363,429,442,for.167,for.221).CCLS.) and @pd>=20040108	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/28 10:29
3	2	(amorphizing amorphization amorphized amorphous) with (ion implant implantation implanting implanted) and ((438/222,226,357,360,363,429,442,for.167,for.221).CCLS.) and @pd>=20040108	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/28 10:29
-	220	(amorphizing amorphization amorphized amorphous) with (ion implant implantation implanting implanted) same (trench groove recess recessed grooved) and (438/$6 257/$6)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/28 10:28
-	112	(amorphizing amorphization amorphized amorphous) with (ion implant implantation implanting implanted) with (trench groove recess recessed grooved) and (((amorphizing amorphization amorphized amorphous) with (ion implant implantation implanting implanted) same (trench groove recess recessed grooved) and (438/$6 257/$6)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/28 08:38
-	49	(amorphous) near4 (layer film si silicon) with (deposit$4 cvd) and (((amorphizing amorphization amorphized amorphous) with (ion implant implantation implanting implanted) with (trench groove recess recessed grooved) and (((amorphizing amorphization amorphized amorphous) with (ion implant implantation implanting implanted) same (trench groove recess recessed grooved) and (438/$6 257/$6)))))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/28 08:40
-	2	("20020094678").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/28 08:53
-	1	jp-07130679-$.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/28 10:03
-	2	("6537873").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/28 10:03

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